# molex

Part Number: 554871419

Product Description: 2.00mm Pitch MicroTPA Wire-to-Board Header, Vertical, Shrouded, High Wall Type, with Inner Positive Lock, 14

Circuits

Series Number: 55487

Status: New Business Not Supported Product Category: PCB Headers and

Receptacles



#### **Documents & Resources**

### **Product Environment Compliance**

#### Compliance

GADSL/IMDS	Not Relevant
China RoHS	<b>©</b>
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2- 21
REACH SVHC	Not Contained per D(2023)3788-DC (14 Jun 2023)
EU RoHS	Compliant per EU 2015/863

### Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

#### Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

## EU RoHS Certificate of Compliance

#### **Part Details**

## General

Status	New Business Not Supported
Category	PCB Headers and Receptacles
Series	55487
Description	2.00mm Pitch MicroTPA Wire-to- Board Header, Vertical, Shrouded, High Wall Type, with Inner Positive Lock, 14 Circuits
Application	Signal, Wire-to-Board
Component Type	PCB Header
Product Family	MicroTPA Connector System
Product Name	MicroTPA
UPC	822348180752

# Agency

UL	E29179

## Electrical

Current - Maximum per Contact	2.5A
Voltage - Maximum	250V

# Physical

Breakaway	No
Circuits (Loaded)	14
Circuits (maximum)	14
Color - Resin	Natural
Durability (mating cycles max)	30
First Mate / Last Break	No
Flammability	94V-0
Glow-Wire Capable	No
Guide to Mating Part	No
Keying to Mating Part	None
Lock to Mating Part	Yes
Mated Height	17.70mm
Material - Plating Mating	Tin
Material - Plating Termination	Tin

Material - Resin	Nylon
Net Weight	1612.160/mg
Number of Rows	1
Orientation	Vertical
Packaging Type	Tray
PC Tail Length	3.30mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.60mm
Pitch - Mating Interface	2.00mm
Polarized to Mating Part	Yes
Shrouded	Fully
Stackable	No
Temperature Range - Operating	-40° to +105°C
Termination Interface Style	Through Hole

This document was generated on Sep 27, 2023